

In-situ Fabrication of Topological Superconducting Hybrids

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Topological Insulators (with Cap)

Reason for band inversion: Chemical bonding, Crystal field splitting, Spin-orbit coupling. Large Spin-orbit coupling leads to band inversion.

2nm of in situ Aluminium capping immediately oxidizes after exposure to air and in this way protects the pristine properties of the surface states.

Lang et al. (2012) ACS Nano 6, pp 295-302

H. Zhang et al. Nature Physics 5, 438 (2009)

Majorana Bound State

Shifting the Fermi level

Further reduce 2π modes

Wiedermann et al. Nature Comm. 7, 10303 (2015)

Quasi 1D topological Josephson Junctions

Protective AlOx Capping Width $\le 90\text{nm}$

Topological PN-Heterostructure

$k_F < 0.1\text{ nm}^{-1}$

$\Delta F > 90\text{ nm}$

Fermi Level adjusted to Dirac-Point

Adjusting E_F to Dirac-Point

Pure Sb_2Te_3 is p-type doped, due to Sb vacancies and Sb_{Te} antisites.

Pure Bi_2Te_3 is n-type doped, due to Te_{Bi} antisites.

By growing a stack of p-type Sb_2Te_3 on top of n-type Bi_2Te_3 one can shift the Fermi level through the cone and adjust it to the Dirac-Point.

The small k_F leads to a $\Delta F > 90\text{ nm}$!

Eschbach et al. (2015) Nat. Comm. 6, 8816

Shapiro steps measurements

$f = 3.0\text{ GHz}$, $f = 3.8\text{ GHz}$, $f = 4.6\text{ GHz}$, $f = 5.0\text{ GHz}$

$f = 5.5\text{ GHz}$, $f = 6.5\text{ GHz}$, $f = 7.8\text{ GHz}$, $f = 10\text{ GHz}$

@T = 1.5 K

Stencil Lithography

$I_c = 6.5\text{ }\mu\text{A}$
 $I_{c,r} = 2.5\text{ }\mu\text{A}$
 $R_n = 50\text{ }\Omega$
 $I_c R_n = 325\text{ }\mu\text{A}$

@T = 12 mK

100 nm, 20 nm

Selective Growth

Substrate fabrication and selective growth:
a) Clean Si.
b) SiO_2 and Si_3N_4 deposition.
c) Nanopatterning (EBL and RIE).
d) HF dip.
e) Selective TI growth.
f) In situ Al capping.

a) $T_{\text{Sub}} = 280^\circ\text{C}$: TI grows in Si trenches and on top of Si_3N_4 .
b) $T_{\text{Sub}} = 290^\circ\text{C}$: TI growth selectively only on Si.
c) $T_{\text{Sub}} = 300^\circ\text{C}$: TI growth nowhere.
d) Al capping deposited on top of filled trenches at $T_{\text{Sub}} = -30^\circ\text{C}$.

Grown Majorana-Qubits

Superconductor (blue) via Stencil Lithography

Topological insulator (light grey) via selective growth

3-8 : braiding (x n)